

IN THE CLAIMS:

The following is a list of all pending claims. Please revise the claims to read as follows:

1-31 cancelled.

32. (Currently Amended) The method of claim [[31]] 35 wherein said channel permits the removal of residual flux.

33. (Currently Amended). the method of claim [[31]] 35 wherein the chip carrier has a first coefficient of thermal expansion different from a coefficient of thermal expansion of the semiconductor device.

34. (Currently Amended). The method of claim [[31]] 35 wherein the chip carrier has a first coefficient of thermal expansion different from a coefficient of thermal expansion of the intermediate mounting substrate.

35. (Currently Amended) ~~The method of claim 31 wherein~~ A method of underfilling a gap between a multi-sided semiconductor device and a chip carrier on which it is mounted to encapsulate a plurality of electrical connections formed therebetween wherein said chip carrier is mounted on an intermediate mounting substrate and the intermediate mounting substrate is adapted for connection to a printed circuit board, comprising

forming a channel extending through said intermediate mounting substrate and said chip carrier to said gap; and

dispensing through said channel an under-fill material into said gap,

said intermediate mounting substrate having a coefficient of thermal expansion different from a coefficient of thermal expansion of the chip carrier and smaller than a coefficient of thermal expansion of the printed circuit board.